

(Sr.) Process Integration Engineer (m/f/d) – SiC Backside Treatment

About the role

Fueled by our goal to become one of the top players in the Power Discretes field with a large growth potential driven by the rapidly expanding markets, we are currently building up a highly talented and ambitious SiC R&D team to grow into the next level. As the (Sr.) Process Integration Engineer for SiC Backside Treatment Processes, you will play an essential part in our strive to become a powerhouse in the electronics field.

What you will do

- Develop new wafer process modules on backside treatment tools for SiC wafers (lamination, delamination, grinding, cleaning)
- Execute major process development or integration tasks and build up product and process knowledge
- Leader of small or medium size process integration or optimization projects
- Sub-project leader of process development or integration tasks in complex projects
- Build up and maintain knowledge (technical & procedures) and Business Group internal & external contacts in own field of expertise
- Active member in PC&O Process improvement teams
- Provide technical mentorship to less experienced engineers

What you will need

- Education in Semiconductor Device Physics or Semiconductor Technology and/or Microelectronics, preferably PhD
- Minimum 3 years relevant work experience, depending on educational credentials
- Knowledge of semiconductor devices and industrial semiconductor technology
- Hands on experience in wafer fab process module developments on backside treatment equipment
- Team player with a strong drive to achieve success
- Fluency in German. Good level in English
- Good communication skills, both verbal and in writing

More information?

For more details please contact: john.perez@nexperia.com.

Are you interested in this career challenge?

Please apply directly via our career page:

Location

Hamburg

Employment type

Fulltime

Contract duration

Permanent

Job-id

R-20007275

